

POLLOCK-05TX

POLLOCK Bill Of Materials

< RF Relay – for PARTS LIST >

COMMODITY : RF Receiver module ass'y

No	DESCRIPTION	SPECIFICATION	Q'TY	Ref.NO/Dwg.NO	Mfr./Vendor	REMARK	PRICE	DOMESTIC
1	RF Relay Control PCB	82 X 116 X 1.6t (FR-4 D/S)	1					
2	10A, 1 pole Power Relay(SPDT)	HR703F DC06V	6	RL1-6	HK			
3	DIP DIGITAL CODE 8-SWITCH	FLAT KNOB SLIDE(K8842SMD or DIP)	1	DIP	OTAX			
4	8-BIT MICROCONTROLLERS	MC80F0504	1	CPU	ABOV			
5	LDO Regulator	MIC5205-3.0YM5(150mA)	1	REG3V	Micrel			
6	Step-Down Voltage Regulator	LM2576HV-5.0V	1	REG5V	National			
7	Switching Transistor(NPN)	2N2222	6	QL1-6	KEC			
8	Small Switching Diode	KDS 160	6	DL1-6	KEC			
9	1A Rectifier Diode(DO-214AC(SMA))	SMD Type 1N4001-1N4007	1	DP1				
10	Schottky barrier rectifier Diode	SS34(SMC, 1N5819 SMD type)	1	DZ1	GALAXY			
11	Indicator LED(RED)	LED 0603 RED(M01-0603SRC-P)	1	LED	Light			
12	Terminal(10P)		1	CON1	chunjee			
13	Power Inductor(100uH)	LPF1040T-101M	1	LPF	ABCO			
14	CHIP INDUCTOR(1uH, BEAD FILTER)	F1-B1608-102KJT	3	BD1-3	CERATECH			
15	AXIAL BEAD Filter	BF-S-2070-A0B	2	BDGND, BDVCC	SAMHWA			
16	CHIP INDUCTOR(15nH)	C1-B1608-150KJT	1	LA1	CERATECH			
17	CHIP INDUCTOR(24nH)	C1-B1608-240KJT	1	LA2	CERATECH			
18	RESONATOR(4MHz)	4MHz	1	RES	C,Q			
19	CHIP Ceramic Cap.(0.1uF 2012)	CL10F104ZANC(#2012 F 100nF 50V)	7	CR1-3,CR5-6, CP1-2	S.S.E			
20	CHIP Ceramic Cap.(470P)	CL10B471KBNC(#1608 B 470P)	2	CP11, CN1	S.S.E			
21	CHIP Ceramic Cap.(1uF) 105	CL10F105ZANC(#1608 F 1000nF)	7	CL1-6, CP6	S.S.E			
22	CHIP Ceramic Cap.(0.1uF)	CL10F104ZANC(#1608 F 100nF)	4	CP4-5, CP7-8	S.S.E			
23	CHIP CERAMIC CAPACITOR(33PF COG)	CL05C330JBNC(#1608 CH 33PF)	1	CA1	SAMSUNG			
24	TANTALUM-Cap.(47uF/6.3V)	10uF/6.3V "B"	2	CP9-10	SSE			
25	TANTALUM-Cap.(100uF/6.3V)	10uF/6.3 "C"	1	CP5V1	SSE			
26	SMD ALUMINUM CAPACITORS(MV Series)	47uF/50V	2	CP3	Samyoung			
27	SMD ALUMINUM CAPACITORS(MV Series)	470uF/10V	2	CP5V	Samyoung			
28	Chip Resistor (0ohm)	RC1608J000C8(0ohm J 000)	1	JP	S.S.E			
29	Chip Resistor (47ohm)	RC1608J470C8(47 ohm J 470)	1	RV1	S.S.E			
30	Chip Resistor (470ohm)	RC1608J471C8(470 ohm J 471)	1	RLED	S.S.E			

31	Chip Resistor (10Kohm)	RC1608J103CS(10K ohm J 103)	8	RY1-6, RN1,R11	S.S.E			
32	Chip Resistor (4.7Kohm)	RC1608J473CS(4.7K ohm J 472)	6	RY11,22,33,44,55,66	S.S.E			
33	Chip Resistor (120ohm 1/2Watt)	RC1608J000CS(0ohm J 000)	6	RS1-6	S.S.E			
1	RF RX Module PCB	12.6 X 32 X 1.6t (FR-4 D/S)	1					
2	RF RX IC	MICRF211(QSOP16)	1	RXIC1	Micrel			
3	Crystal(13.52127MHz, HC49)	SA-13.521270-F-10-H-30-30-X	1	X1	10pF load capacitance, 30ppm			
6	CHIP INDUCTOR(39nH)	C1-B1608-390KJT	1	LM1	CERATECH			
23	CHIP CERAMIC CAPACITOR(33PF COG)	CL05C330JBNC(#1608 CH 33PF)	1	CM1	SAMSUNG			
10	CHIP CERAMIC CAPACITOR(47PF COG)	CL10C470JBNC(#1608 CH 47PF)	1	CM5	SAMSUNG			
11	CHIP Ceramic Cap.(0.1uF)	CL10F104ZANC(#1608 F 100nF)	3	CM4, 6, 8	S.S.E			